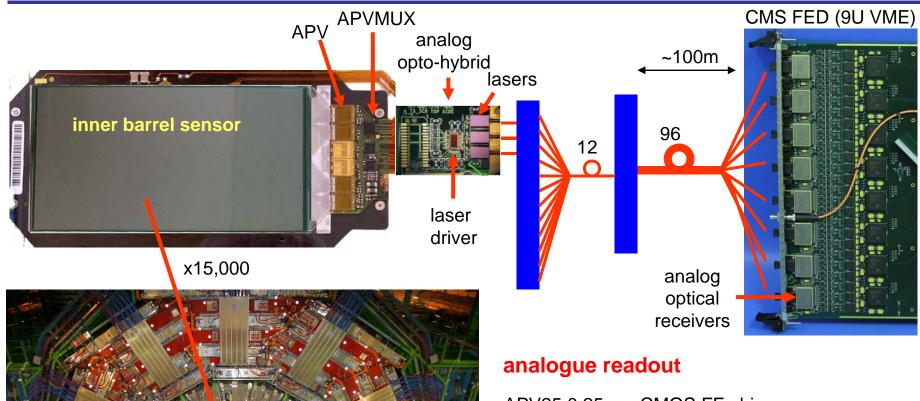


## OUTLINE

brief review of LHC strip readout architecture proposed architecture for SLHC front end amplifier design in 130nm system architecture ideas triggering possibilities with strips summary

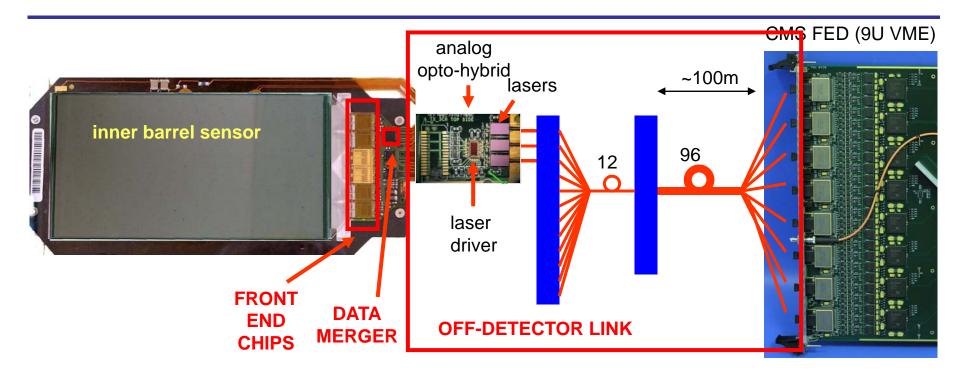
Mark Raymond – Imperial College London

## **CMS LHC Si strip readout system**



APV25 0.25 μm CMOS FE chip APV outputs analog samples @ 20 Ms/s APVMUX multiplexes 2 APVs onto 1 line @ 40 MHz Laser Driver modulates laser current to drive optical link @ 40 Ms/s / fibre O/E conversion on FED and digitization @ ~ 9 bits (effective)

## **CMS LHC strip readout system**

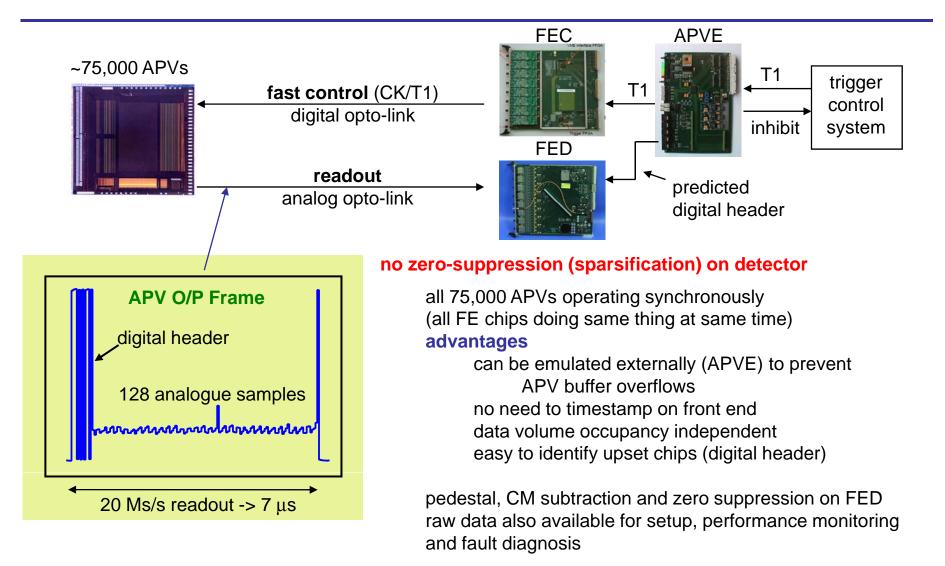


LHC strip readout system actually rather simple - breaks down into 3 components

### FRONT END CHIPS APV25 DATA MERGER APVmux – multiplexes outputs of 2 APVs onto one line OFF-DETECTOR LINK analogue – APVmux output drives laser driver => 2 APVs per off-detector fibre

system simplicity comes from choosing not to zero-suppress (sparsify) on front end

## LHC control / readout chain overview



analog, unsparsified readout provides relatively simple and robust system

## **SLHC challenges for CMS tracker**

#### 1) power

higher granularity => more FE chips electronics related material dominates existing material budget (cabling, cooling) & we want to reduce this

#### 2) triggering

not possible to keep L1 trigger rate at 100 kHz without contribution from tracker

#### => new features and existing architectures need re-design and replacement

#### what we like about our present system

analog pulse height info made possible by custom analog off-detector link no on-detector sparsification system simplicity - no fluctuating data volumes event-to-event

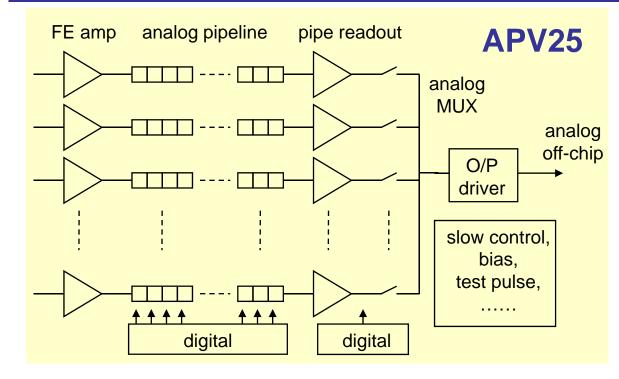
#### what must change for SLHC

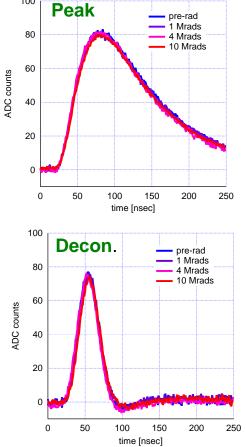
off-detector links -> high speed digital => digitization on FE if want to retain pulse height info

#### will look at pros and cons of different FE chip architectures

#### **CMS tracker material budget** All Tracker 1.4 Beam Pipe 1.2 Sensitive Electronics Support Cooling X/X<sub>0</sub> 🗖 Cable 0.4 0.5 1.5 2 η

## LHC front end chip architecture





100

#### existing LHC architecture – APV25

slow 50 nsec CR-RC FE amplifier, analog pipeline, 2.7 mW/channel

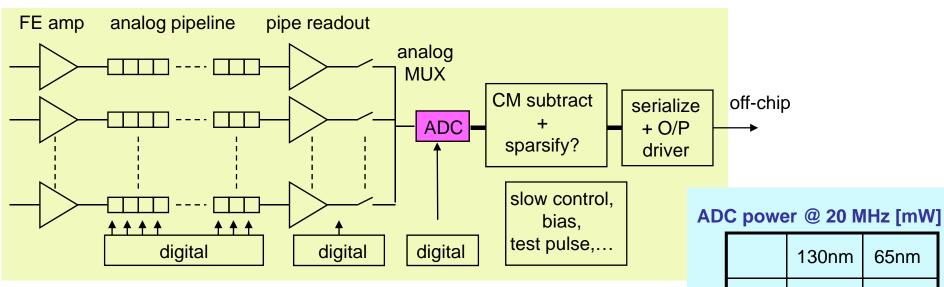
#### peak/deconvolution pipe readout modes

peak mode -> 1 sample -> normal CR-RC pulse shape

deconvolution -> weighted sum of 3 consecutive samples combined to give single BX resolution

all analog approach – not compatible with digital off-detector data transmission moving to SLHC – if want to retain pulse height information – where to digitise?

# "digital APV" architecture



#### digitization before pipeline? (on every channel)

early assumptions said no – ADC power too high (ITRS 2003) still valid? - maybe not in future processes (90 nm, 65 nm) some new ADC architectures beating previous power predictions \* but negligible power / channel still some way off

# 130nm 65nm 8 bits 6.4 2.5 6 bits 1.6 0.6

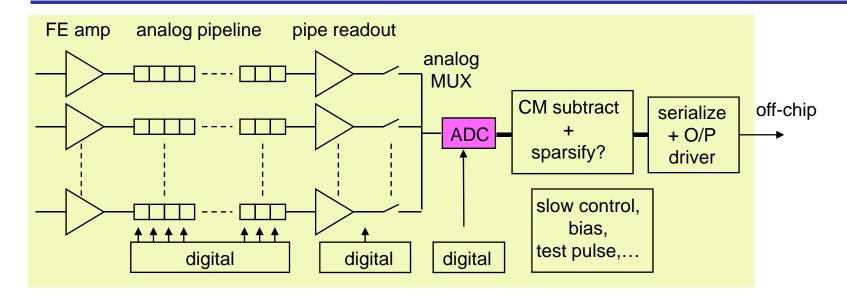
from ITRS roadmap 2003

#### digitization after pipeline?

negligible power/channel **is** achievable - ADC power shared between all front end channels analog pipeline remains so could retain slow shaping + analog deconvolution approach

but this architecture still brings some disadvantages

# digital APV architecture disadvantages



very complicated chip – all the complexity of APV + more

fast ADC required

data volume means sparsification necessary to keep data at manageable levels on-chip CM subtraction probably necessary (analogue pipeline contributes) off-detector FED features in existing system

analogue pipeline using gate capacitance may still be possible in 130nm – not in finer processes

(plan to increase pipeline length for SLHC)

analogue circuitry throughout chip - harder to achieve supply noise rejection

sparsification leads to on-detector system complexity

extra buffering required (more chips) to cope with varying trigger-to-trigger data volume front-end timestamping

if want to keep simple un-sparsified system => pulse ht. info has to go => binary

## **binary architecture – un-sparsified**

#### what about binary un-sparsified?

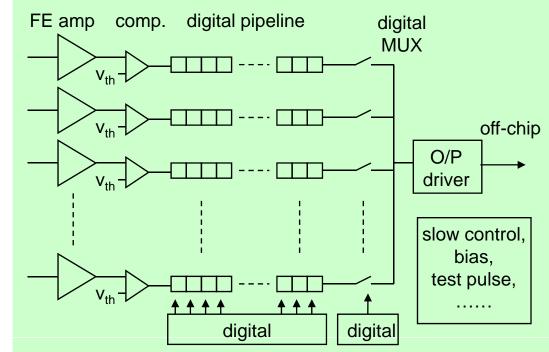
**much** simpler (than digital APV) particularly for pipeline and readout side

need fast front end and comparator => more power here

but no ADC power and much simpler digital functionality will consume less – this architecture **will** be lowest power

binary architecture also compatible with some approaches to track triggering layers

#### can retain system features we like



simpler synchronous system, no FE timestamping data volume known, occupancy independent (no trigger-to-trigger variation)

#### un-sparsified binary is the option we are currently planning to implement

**but** less diagnostics (can measure front end pulse shape on every channel in present system) loss of position resolution common mode immunity

## front end amplifier design

binary FE design has begun in 130 nm CMOS

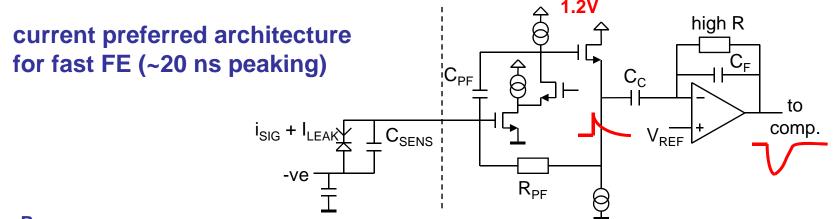
#### preliminary specifications and assumptions

n-on-p sensor (signal current flows out of amplifier) promising option for rad hard sensors

need to tolerate leakage current up to ~ 1  $\mu$ A allows DC coupling for lower cost sensors

need to be fast enough for acceptable timewalk aim for peaking time ~ 20 nsec

# 130nm front end amplifier



#### Preamp

#### **NMOS I/P device**

no noise penalty - 1/f corner low enough (simulation & published measurements) better connection to sensor for PSR (sensor bias decoupling and I/P FET source both at GND)

#### real resistor feedback

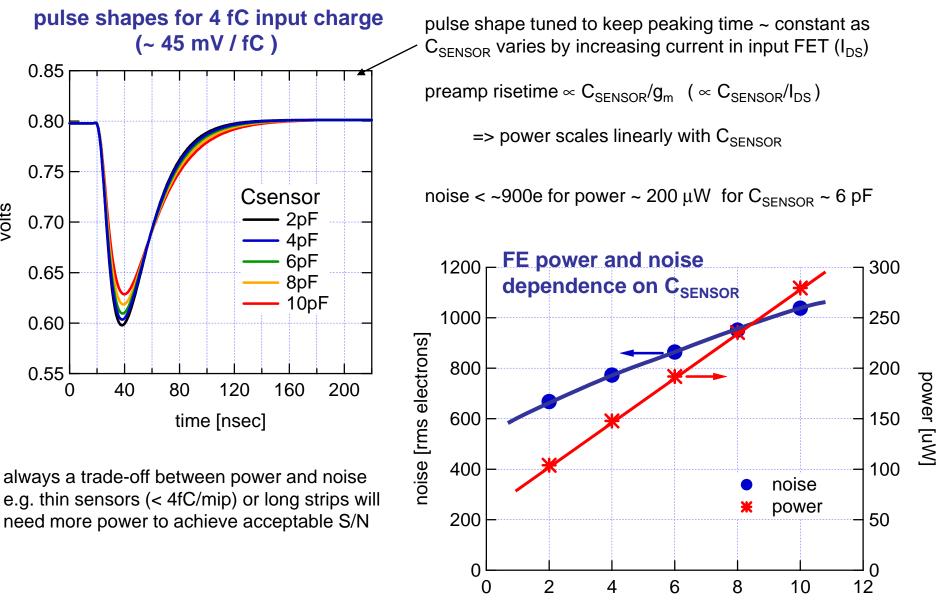
low Rpf (200k) allows DC leakage to be accommodated (1 μA -> 200 mV) uses highest resistance technology in process (1k7/square poly, +/-20%) Rpf//Cpf = 200k//100fF = 20 ns decay time constant of preamp (no pile-up) 200k contributes ~ 220e

#### Postamp

provides gain & risetime provides integrating time constant AC coupled to preamp (DC shift due to leakage decoupled) O/P DC level set by  $V_{REF}$  – defines DC level at output (comparator input)

#### will show some simulated performance pictures - all results at preliminary stage

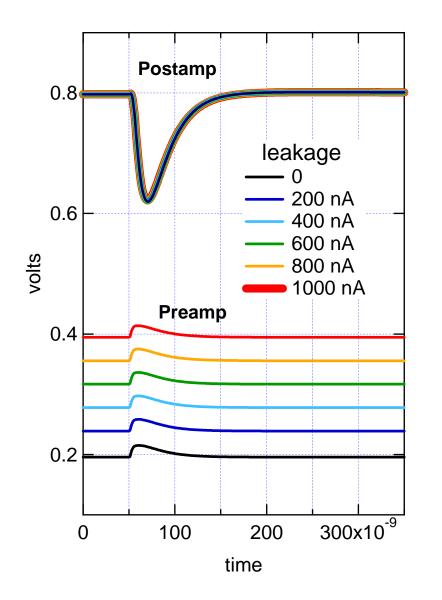
## binary FE pulse shape and noise



volts

Csensor [pF]

## **Effects of leakage current**



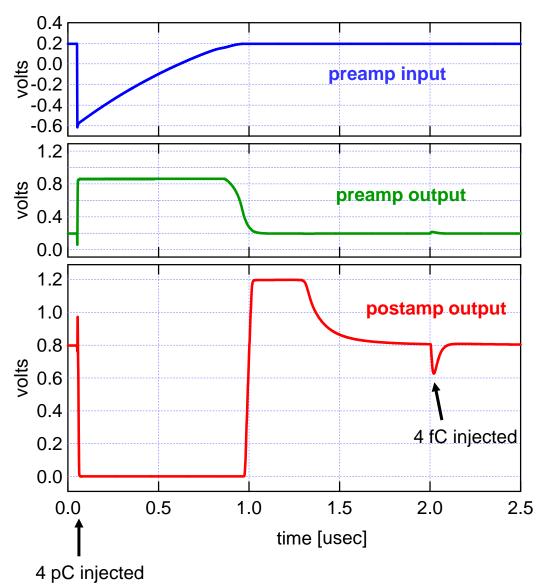
postamp output unaffected (AC coupled)

preamp output shows DC shift across R<sub>PF</sub>

1  $\mu$ A leakage contributes ~ 440e noise to be added in quadrature to amplifier noise (short shaping time helps with parallel noise)

e.g. 900 (total amplifier for  $C_{SENSOR} \sim 6 \text{ pF}$ ) + 440 (leakage) = ~1000e total

## response to overload



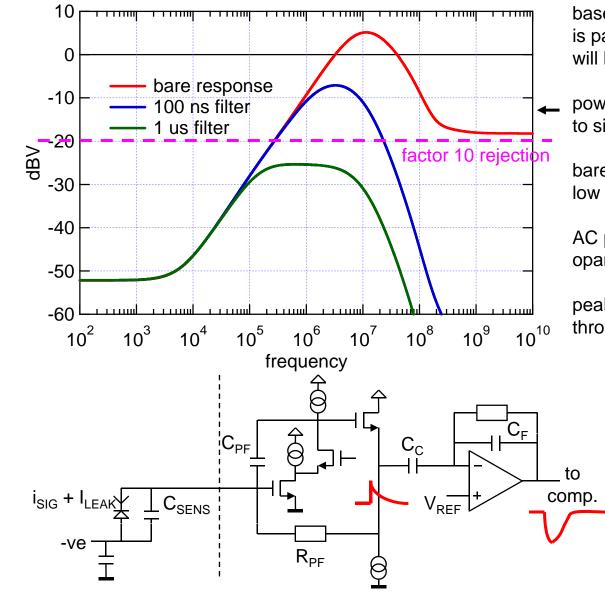
overload behaviour well-controlled

low  $R_{PF}$  beneficial

front end recovers from 4 pC signal and sensitive to normal signals within 2.5  $\mu s$ 

=> no "APV-like" hips effect

# power supply rejection



baseline choice for CMS tracker powering is parallel powering (DC-DC) so PSR will be an issue

 power supply rejection at postamp output to sinusoidal waveform on positive supply rail

bare response shows good rejection at low frequency, peaking at ~10 MHz

AC preamp/postamp coupling together with opamp postamp gives good low f behaviour

peaking at ~10 MHz (gain) due to coupling through bias circuits

can improve with realistic filtering, but would prefer some rejection at all frequencies to start with

needs further study

## power estimate

#### 130nm binary chip – non-sparsified readout

#### **0.5 mW / channel** seems like an achievable target (c.f. 2.7 mW for APV25)

	power / channel
preamp/postamp e.g. 20 nsec peaking time, short strips C <sub>SENSOR</sub> ~ 5pF	180 μW
comparator estimate from preliminary simulations	20 μW
miscellaneous digital estimate loosely based on APV pipe and control logic	60 µW
mux + output driver + just guess nominal figure to bring overall power to 0.5 mW will depend on implementation. e.g. choice of electrical protocol can hope for saving here, but good to have contingency	240 μW
digital is biggest uncertainty, and maybe largest contributor can consider running at lower voltage (dig. power ~ V <sup>2</sup> ) should keep power rails separate on chip to keep option open	

# full prototype in 1<sup>st</sup> iteration

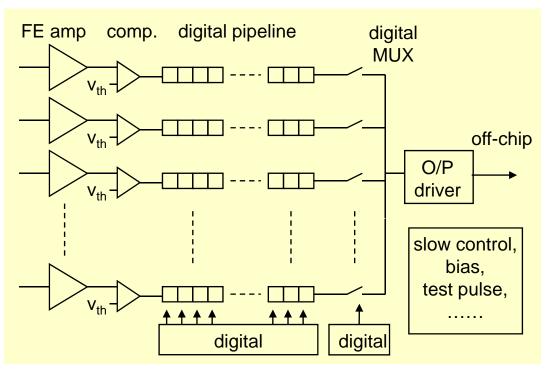
relative simplicity of unsparsified binary architecture means can go for complete chip on timescale ~ 1year less risky than complex "digital APV"

will learn a lot sooner rather than later

will also provide collaborators with something to use to evaluate sensors and modules

choose front end most likely to suit SLHC (e.g. n-side readout?) (can still submit test structures for alternative front ends)

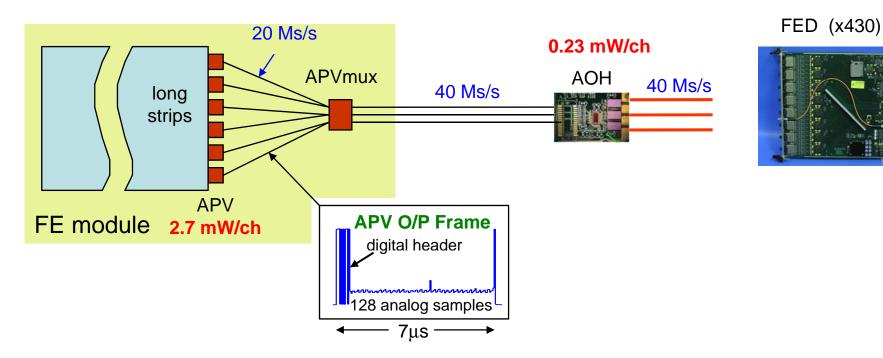
## CBC (CMS Binary Chip)



may leave out some features e.g. bias gen., test pulse, I<sup>2</sup>C I/F

but should have main functionality: pipeline, pipe control logic, and mux., trimDAC for comparator thresholds,

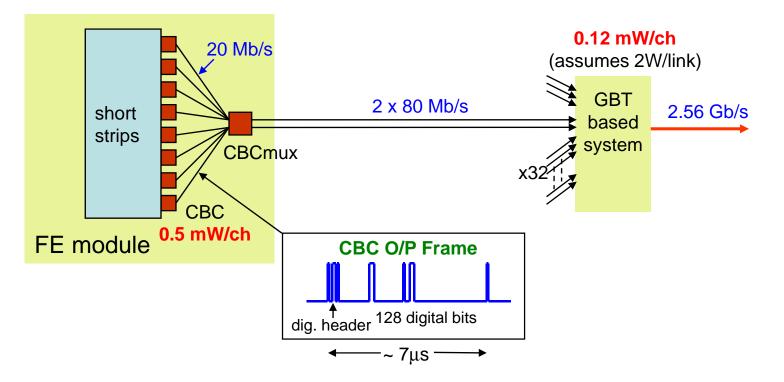
# LHC -> SLHC strips readout system



## recap LHC

APV provides analogue unsparsified output data at 20 Ms/s data frame 7 μs => 70% of off-detector bandwidth used for 100 kHz trigger 2 APVs data interleaved at 40 Ms/s on one electrical line (differential) one-to-one correspondence to off-detector fibre (i.e. still 2 APVs / fibre) link power <10% overall channel power

## LHC -> SLHC strips readout system



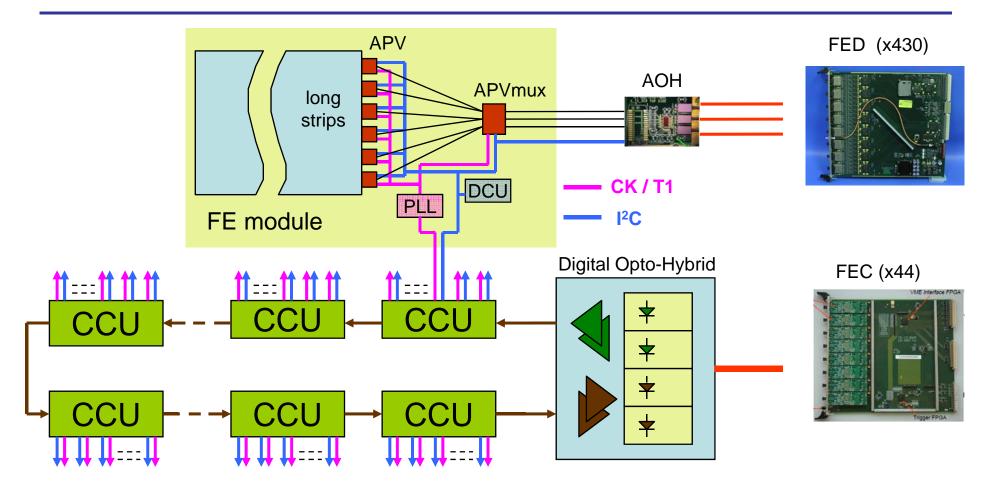
## moving to SLHC - early ideas

binary unsparsified, but output frame format can be similar to APV (just hits, not analog values) CBC could provide output data at 20 Mb/s

keep data frame ~7 µs

=>4 CBCs data multiplexed at 80 Mb/s onto one electrical line (GBT lane) 32 x 80 Mb/s lanes combined on 2.56 Gb/s off-detector fibre (128 CBCs / fibre) link power ~ 20% overall channel power (assumes 2W / link)

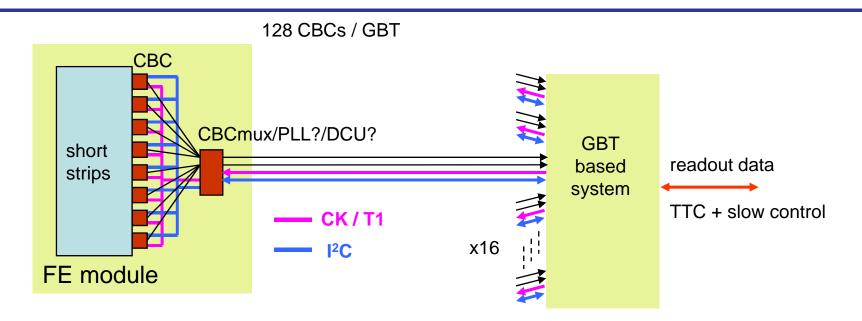
## LHC strips readout & control system



CCU distributes CK/T1 and I<sup>2</sup>C control busses to up to 16 FE modules PLL chip recovers CK and T1 (missing clock pulse) on FE module DCU chip monitors FE currents, voltages and temperatures I<sup>2</sup>C used for programming APVs, reading DCU monitoring info, setting up AOH

CCU chip electrical control ring architecture on front end reduces no. of control fibres required

## SLHC strips readout & control system



system design here is not yet well defined (my thoughts here)

should be much simpler (on-detector) than LHC system e.g. could combine mux/PLL/DCU functionalities in one chip?

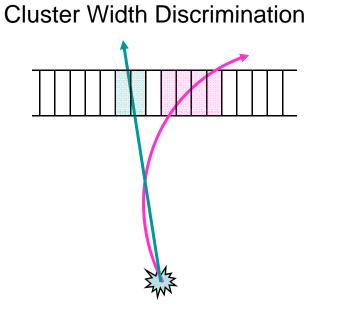
GBT based system means GBT + whatever else is needed (if anything) does this map to current GBT functionality?

I<sup>2</sup>C and CK/T1 could be common to a number of FE modules

# track triggering

## two concepts compatible with microstrip tracker

W.Erdmann R.Horisberger \*

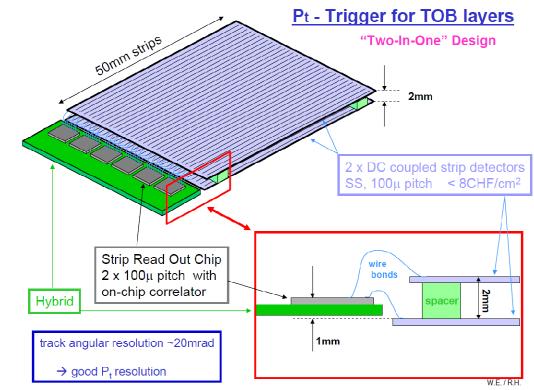


high  $P_T$  track -> narrow cluster width

see: Track momentum discrimination using cluster widthin Si strip sensors, *G.Barbagli, F.Palla, G. Parrini,* TWEPP07

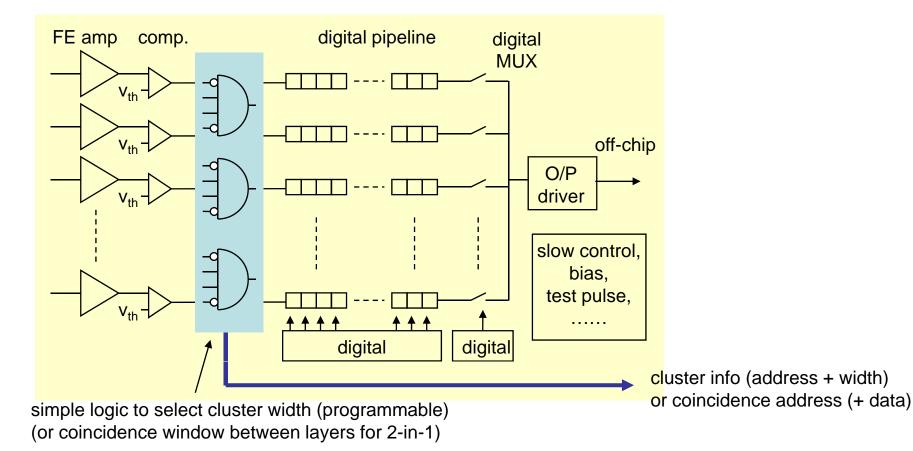
## Two-In-One Design

bond stacked upper and lower sensor channels to adjacent channels on same ASIC no interlayer communication - no extra correlation chip just simple logic on readout chip, looking at hits (from 2 layers) on adjacent channels



\*http://indico.cern.ch/getFile.py/access?contribId=3&sessionId=0&resId=0&materialId=0&confId=36580

# triggering logic on FE chip



#### **binary FE required**

comparator needed to feed trigger logic

#### system architectures are evolving

e.g. further ideas to combine clusters in data concentrator chip before transmission off-module, see: <a href="https://twiki.cern.ch/twiki/pub/CMS/SLHCTrackTriggerPrimitiveTaskForce/TriggerTaskForce14Jan09.pdf">https://twiki.cern.ch/twiki/pub/CMS/SLHCTrackTriggerPrimitiveTaskForce/TriggerTaskForce14Jan09.pdf</a> - F.Palla 23

## summary & plans

#### main SLHC design challenges are power and triggering

#### current plans for CMS strip tracker are:

#### binary unsparsified architecture

lose pulse height info, but retain some system features we like should offer lowest possible FE chip power

full-size 130nm chip on first iteration – hope to submit this year front end amplifier already under design – other parts will begin soon specifications at preliminary stage – will develop over coming months

binary architecture already compatible with some track-trigger approaches under consideration relative simplicity of readout scheme should allow to free-up resources to help develop track-trigger solution ("two-in-one", cluster-width, or stacked pixels)

=> more chips to develop

#### final words

time is short – chip and system design process is just the start, shouldn't forget many issues to confront: testing – bare chips and modules new powering schemes, SEU immunity, low temperature operation,... assembly techniques may differ from past (wire -> bump-bonding?) chip production: more chips than in past – longer test time and/or more test equipment/centres has to start some years (maybe 5?) before tracker installation